



Material Content Data Sheet



Sales Product Name		6ED003L02-F2		Issued		20. July 2018		
MA#		MA001726912						
Package		PG-TSSOP-28-1		Weight*		107.03 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.034	2.84	2.84	28351	28351
leadframe	non noble metal	nickel	7440-02-0	14.398	13.45		134517	
	non noble metal	iron	7439-89-6	19.882	18.58	32.03	185762	320279
wire	noble metal	gold	7440-57-5	0.846	0.79	0.79	7906	7906
encapsulation	organic material	carbon black	1333-86-4	0.194	0.18		1817	
	plastics	epoxy resin	-	8.231	7.69		76901	
	inorganic material	silicondioxide	60676-86-0	56.385	52.67	60.54	526806	605524
leadfinish	non noble metal	tin	7440-31-5	1.539	1.44	1.44	14383	14383
plating	noble metal	silver	7440-22-4	1.416	1.32	1.32	13226	13226
glue	plastics	acrylic resin	-	0.221	0.21		2066	
	noble metal	silver	7440-22-4	0.885	0.83	1.04	8265	10331
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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